

## 30V N-Channel Enhancement Mode Power MOSFET

### Description

WMB81N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 30\text{ V}$ ,  $I_D = 81\text{ A}$   
 $R_{DS(on)} < 5.5\text{ m}\Omega$  @  $V_{GS} = 10\text{ V}$   
 $R_{DS(on)} < 9\text{ m}\Omega$  @  $V_{GS} = 4.5\text{ V}$
- Green Device Available
- 100% EAS Guaranteed
- Low Gate Charge
- Low  $R_{DS(on)}$

### Applications

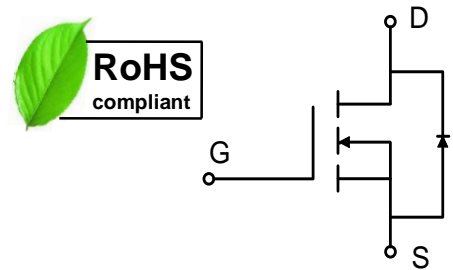
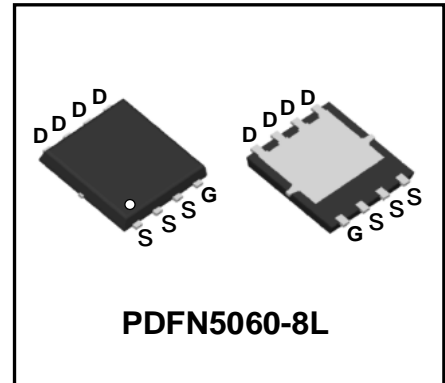
- Power Management Switches
- DC/DC Converter

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source voltage	$V_{DS}$	30	V
Gate-Source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current@10V <sup>1</sup>	$I_D$	$T_C=25^\circ\text{C}$	81
		$T_C=100^\circ\text{C}$	51
		$T_A=25^\circ\text{C}$	15
		$T_A=70^\circ\text{C}$	12
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	160	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	115.2	mJ
Avalanche Current	$I_{AS}$	48	A
Total Power Dissipation <sup>4</sup>	$P_D$	$T_C=25^\circ\text{C}$	59
		$T_A=25^\circ\text{C}$	2
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to+150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	2.1	$^\circ\text{C/W}$



**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V	
Gate-body Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 24V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=55^\circ\text{C}$			-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.7	2.5	V	
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	-	4.8	5.5	m $\Omega$	
		$V_{GS} = 4.5V, I_D = 15A$	-	6	9		
Forward Transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 30A$	-	41	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1\text{MHz}$	-	1880	-	pF	
Output Capacitance	$C_{oss}$		-	267	-		
Reverse Transfer Capacitance	$C_{rss}$		-	185	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$	-	1.7	-	$\Omega$	
Total Gate Charge(4.5V)	$Q_g$	$V_{GS} = 4.5V, V_{DS} = 15V, I_D = 15A$	-	20	-	nC	
Gate-Source Charge	$Q_{gs}$		-	7.6	-		
Gate-Drain Charge	$Q_{gd}$		-	7.2	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 15V, R_G = 3.3\Omega, I_D = 15A$	-	7.8	-	nS	
Rise Time	$t_r$		-	15	-		
Turn-Off Delay Time	$t_{d(off)}$		-	37.3	-		
Fall Time	$t_f$		-	10.6	-		
<b>Drain-source body diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 1A, V_{GS} = 0V$	-	-	1.0	V	
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G = V_D = 0V, \text{Force Current}$	-	-	81	A	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 30A, dI/dt = 100A/\mu s$	-	14	-	nS	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	5	-	nC	

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=48A$
- The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

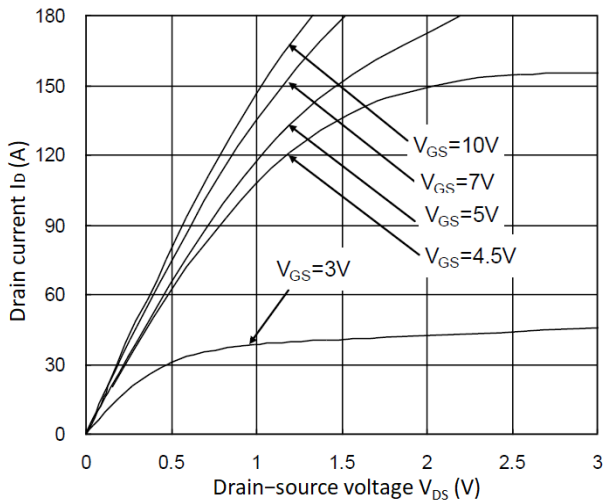


Figure 1. Output Characteristics

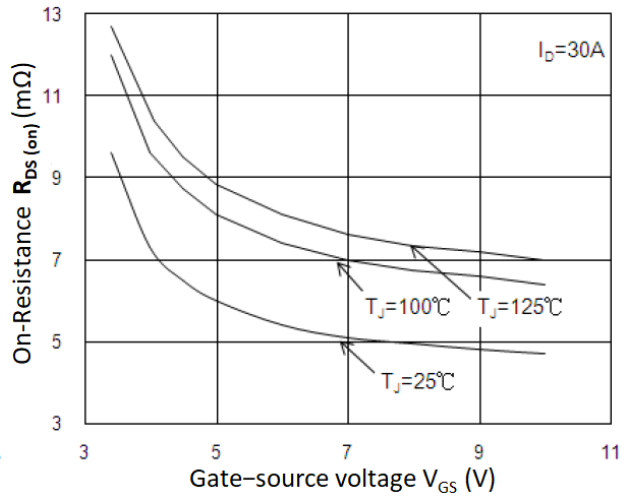


Figure 2.  $R_{DS(on)}$  vs.  $V_{GS}$

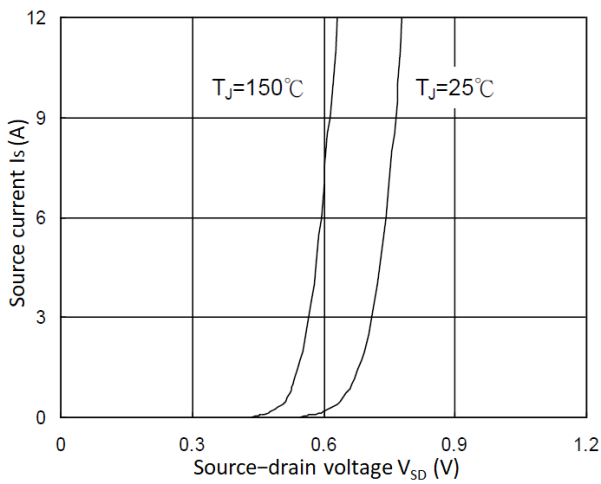


Figure 3. Forward Characteristics of Reverse

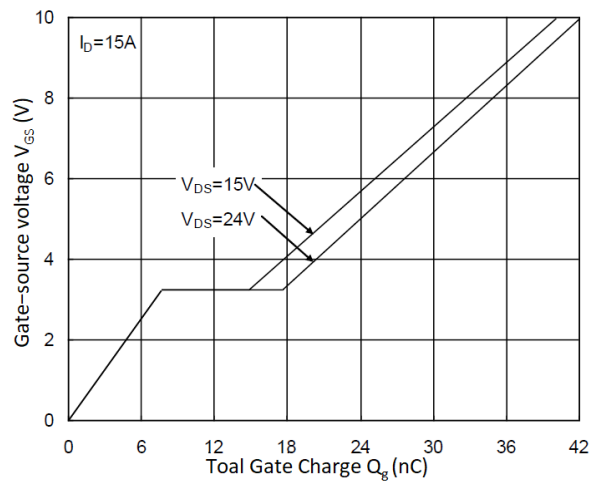


Figure 4. Gate Charge Characteristics

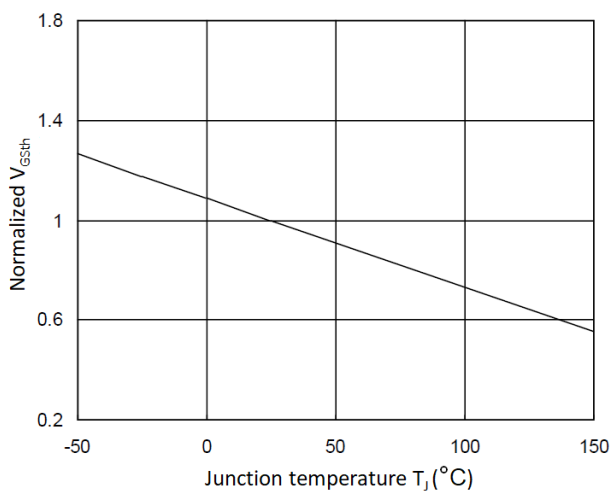


Figure 5. Normalized  $V_{GS(th)}$  vs.  $T_J$

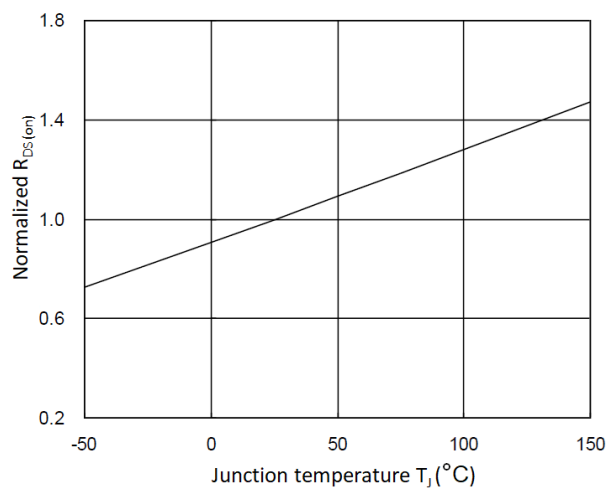


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

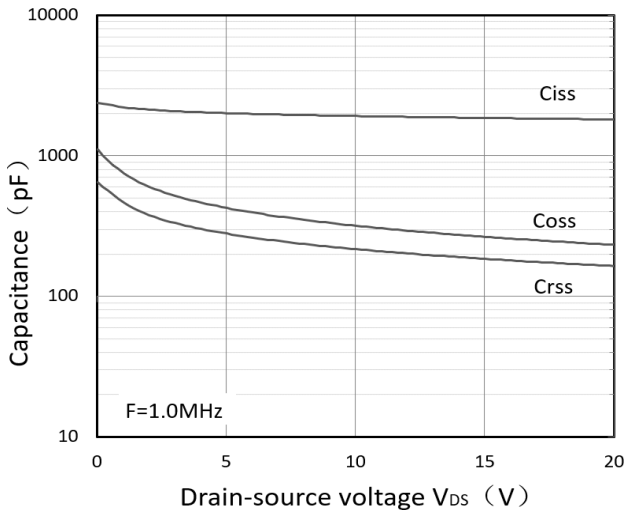


Figure 7. Capacitance Characteristics

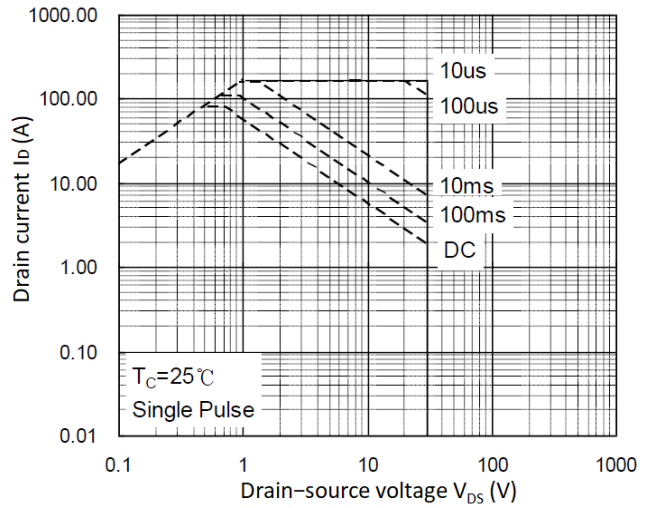


Figure 8. Safe Operating Area

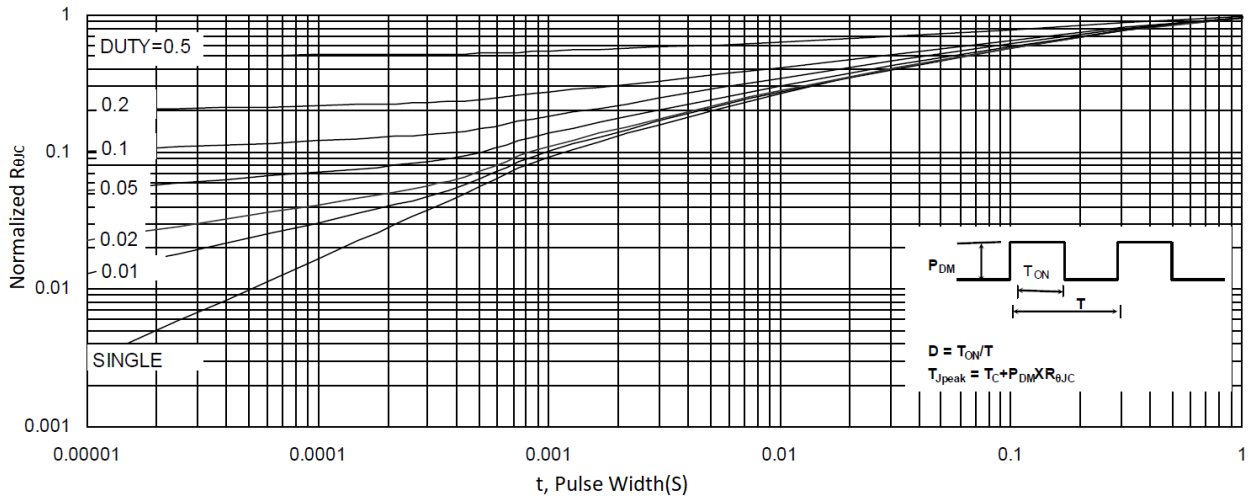


Figure 9. Normalized Maximum Transient Thermal Impedance

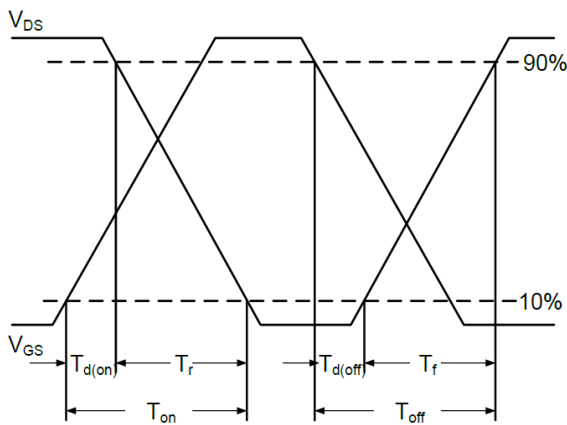


Figure 10. Switching Time Waveform

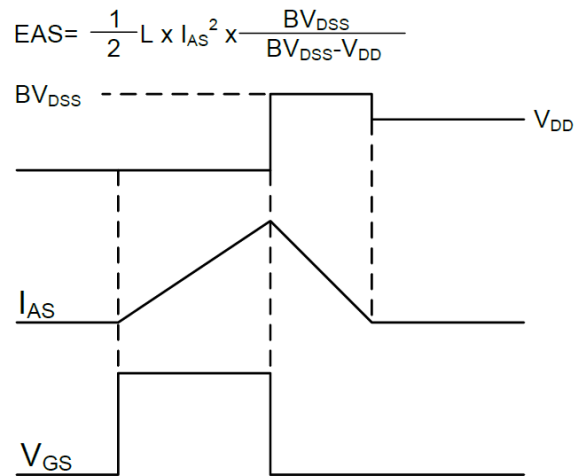
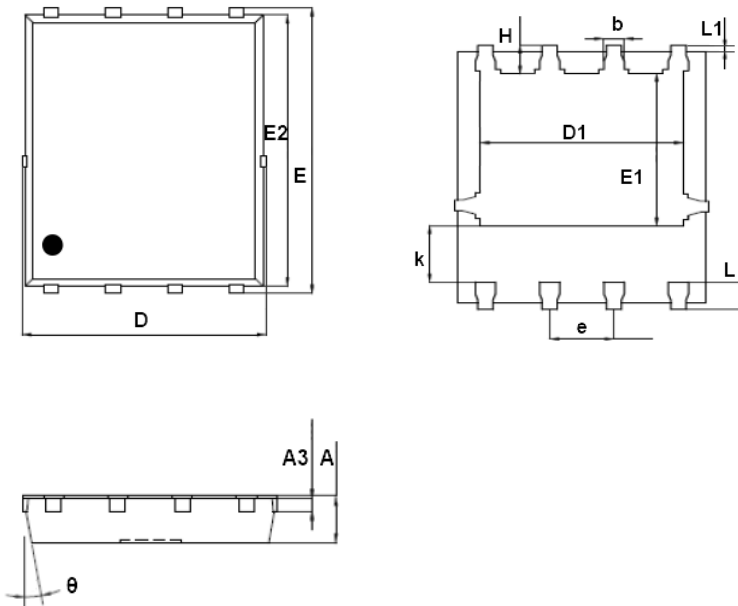


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for PDFN5060-8L

## COMMON DIMENSIONS

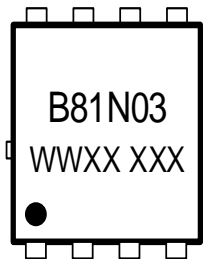


SYMBOL	MM	
	MIN	MAX
A	0.90	1.17
A3	0.20	0.35
D	4.80	5.40
E	5.90	6.15
D1	3.61	4.31
E1	3.3	3.78
E2	5.65	5.85
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
$\theta$	0°	12°

## Ordering Information

Part	Package	Marking	Packing method
WMB81N03T1	PDFN5060-8L	B81N03	Tape and Reel

## Marking Information



B81N03= Device code

WWXX XXX= Date code

## Contact Information

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